

Abstract

The present invention provides a silicone adhesive not reducing wire bondability and not reducing the adhesion of the surface of a semiconductor pellet and a lead frame to sealing resin. Specifically, it provides a silicone adhesive for bonding a semiconductor pellet to a member for mounting the pellet, which comprises an addition reaction curing silicone rubber composition contaminating, upon curing by heating, a glass plate therewith at a contact angle of 70°C or less to the glass plate.